ABSTRACT

Integrated Circuit Package System With Relief

An integrated circuit package system including: providing a die pad with a top, sides, and a bottom, the bottom having a relief with a flat surface and defining a wall and a center pad; mounting a barrier under the bottom of the die pad; mounting an integrated circuit die on the top of the die pad; encapsulating the integrated circuit die and the top and sides of the die pad with the wall preventing encapsulation from flowing along the barrier to reach the center pad; and mounting an external interconnect on the center pad. (Fig. 2)